

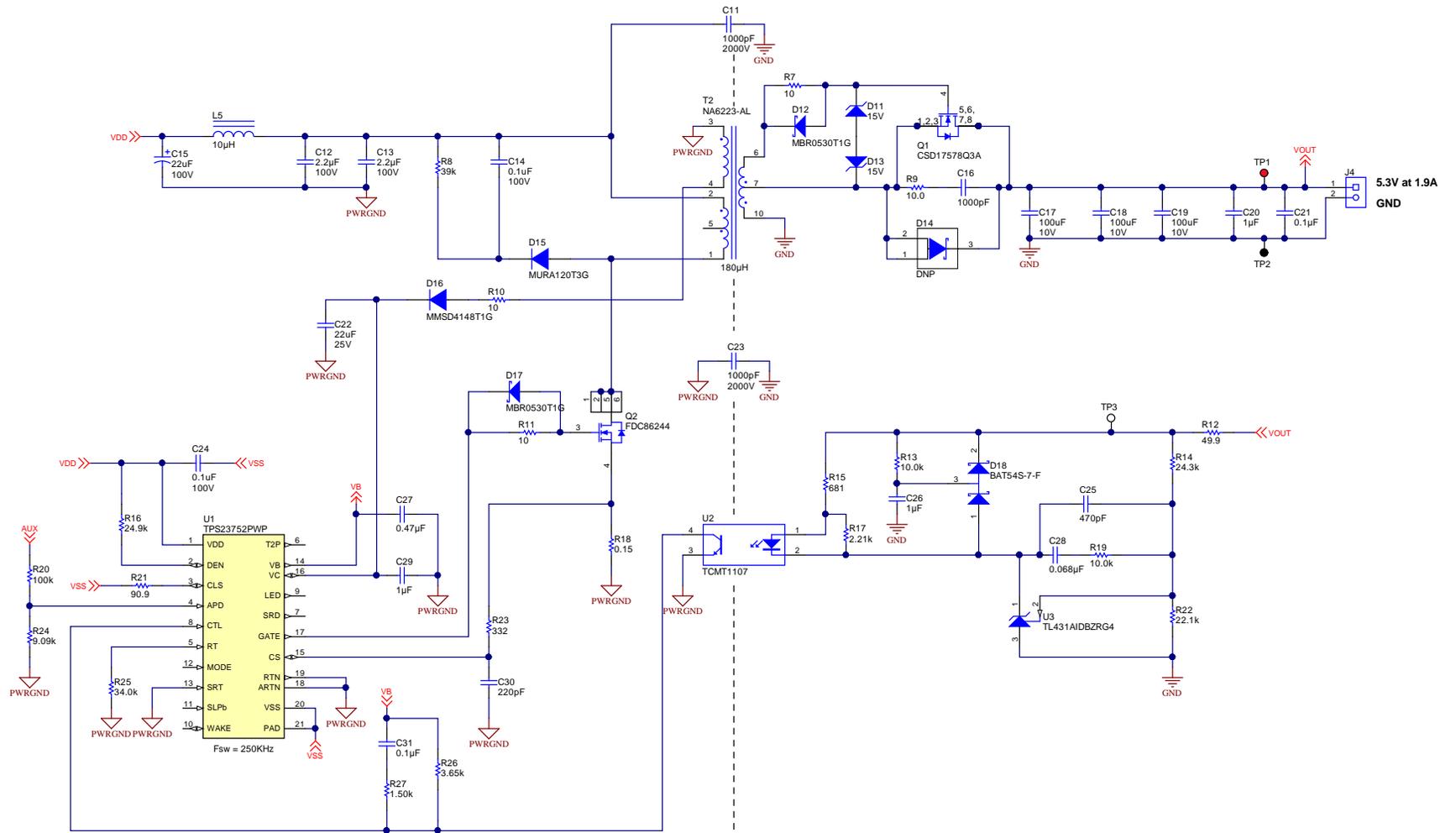
Assembly Notes:

Built on PMP30290 Rev_A PCB

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Designed for: Public Release	Mod. Date: 8/11/2017
Project Title: High Efficiency PoE Flyback Converter	
Number: PMP30290	Rev: B
Sheet Title: PoE Input	Assembly Variant: No Variations
Drawn By: R. Scibilia	File: PMP30290 Rev_B Filter_SchDoc
Engineer: R. Scibilia	Contact: NA





Assembly Notes:

Built on PMP30290 Rev_A PCB

TP3, R12 for test purpose only

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Number: PMP30290	Rev: B	Designed for: Public Release	Mod. Date: 11/14/2017
Assembly Variant: No Variations	Sheet: 2 of 2	Project Title: High Efficiency PoE Flyback Converter	
Drawn By: R. Scibilla	File: PMP30290 Rev_B Power Stage.SchDoc	Sheet Title: Flyback Converter	
Engineer: R. Scibilla	Contact: NA	Assembly Variant: No Variations	Sheet: 2 of 2
			Size: B
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